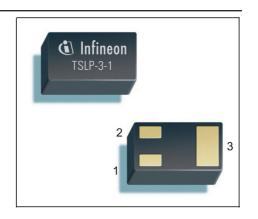


Low Noise Silicon Bipolar RF Transistor

- Low voltage/ Low current operation
- Transition frequency of 14 GHz
- High insertion gain
- Ideal for low current amplifiers and oscillators
- Pb-free (RoHS compliant) and halogen-free thin small leadless package
- Qualification report according to AEC-Q101 available







ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Туре	Marking	Pin Configuration			Package
BFR340L3	FA	1 = B	2 = E	3 = C	TSLP-3-1

Maximum Ratings at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{\sf CEO}$	6	V
Collector-emitter voltage	V_{CES}	15	
Collector-base voltage	V_{CBO}	15	
Emitter-base voltage	V_{EBO}	2	
Collector current	I _C	10	mA
Base current	I _B	2	
Total power dissipation ¹⁾	P _{tot}	60	mW
<i>T</i> _S ≤ 120°C			
Junction temperature	TJ	150	°C
Storage temperature	$T_{ m Stg}$	-55 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ²⁾	R_{thJS}	500	K/W

 $^{{}^{1}}T_{\rm S}$ is measured on the collector lead at the soldering point to the pcb

 $^{^2}$ For the definition of R_{thJS} please refer to Application Note AN077 (Thermal Resistance Calculation)



Electrical Characteristics at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage	V _{(BR)CEO}	6	9	-	V
$I_{\rm C}$ = 1 mA, $I_{\rm B}$ = 0					
Collector-emitter cutoff current	I _{CES}	-	-	10	μA
$V_{CE} = 15 \text{ V}, V_{BE} = 0$					
Collector-base cutoff current	I _{CBO}	-	-	100	nA
$V_{\rm CB} = 5 \text{ V}, I_{\rm E} = 0$					
Emitter-base cutoff current	I _{EBO}	-	-	1	μA
$V_{\rm EB} = 1 \text{ V}, I_{\rm C} = 0$					
DC current gain	h _{FE}	90	120	160	-
$I_{\rm C}$ = 5 mA, $V_{\rm CE}$ = 3 V, pulse measured					



Electrical Characteristics at T_A = 25 °C, unless otherwise specified

Symbol	Values			Unit
	min.	typ.	max.	
g)	T		· T	1
f_{T}	10	14	-	GHz
C_{cb}	-	0.17	0.4	pF
C _{ce}	-	0.13	-	
C_{eb}	-	0.12	-	
NF _{min}	-	1.15	-	dB
G _{ms}	-	17.5	-	-
G _{ma}	-	13	-	dB
$ S_{21e} ^2$				dB
	-	14	-	
	-	10	-	
IP3	-	12.5	-	dBm
P _{-1dB}	-	-1	-	
	g) fT C _{cb} C _{ce} NF _{min} G _{ms} S _{21e} ²	min. g)	min. typ. g) f_T 10 14 C_{cb} - 0.17 C_{ce} - 0.13 NF_{min} - 1.15 G_{ms} - 17.5 $ S_{21e} ^2$ - 14 $IP3$ - 12.5	min. typ. max. g) f_T 10 14 - C_{cb} - 0.17 0.4 C_{ce} - 0.13 - NF_{min} - 1.15 - G_{ms} - 17.5 - $ S_{21e} ^2$ - 14 - $ P3$ - 12.5 -

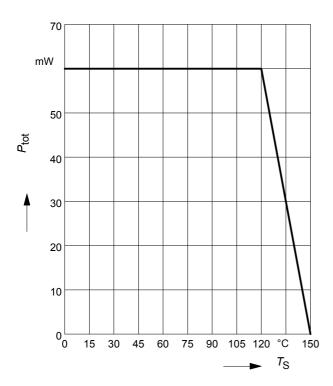
 $^{^{1}}G_{\text{ma}} = |S_{21e} / S_{12e}| (k-(k^{2}-1)^{1/2}), G_{\text{ms}} = |S_{21e} / S_{12e}|$

²IP3 value depends on termination of all intermodulation frequency components.

Termination used for this measurement is 50Ω from 0.1 MHz to 6 GHz



Total power dissipation $P_{tot} = f(T_S)$



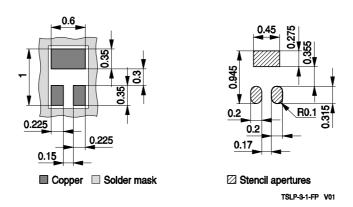


Package Outline Top view Bottom view 0.05 MAX. 0.05 MAX. 0.05±0.035 0.05

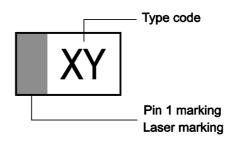
1) Dimension applies to plated terminal

TSLP-3-1-PO V03

Foot Print

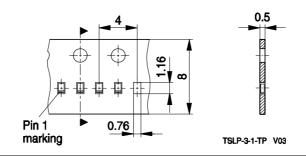


Marking Layout (Example)



Standard Packing

Reel Ø 330 mm: 15.000 Pieces/ Reel





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